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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	4848
Number of Logic Elements/Cells	43632
Total RAM Bits	3538944
Number of I/O	692
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/xilinx/xc2vp40-7ff1152c">https://www.e-xfl.com/product-detail/xilinx/xc2vp40-7ff1152c</a>

implemented. In system mode, a Virtex-II Pro device will continue to function while executing non-test Boundary-Scan instructions. In test mode, Boundary-Scan test instructions control the I/O pins for testing purposes. The Virtex-II Pro Test Access Port (TAP) supports BYPASS, PRELOAD, SAMPLE, IDCODE, and USERCODE non-test instructions. The EXTEST, INTEST, and HIGHZ test instructions are also supported.

### **Configuration**

Virtex-II Pro / Virtex-II Pro devices are configured by loading the bitstream into internal configuration memory using one of the following modes:

- Slave-serial mode
- Master-serial mode
- Slave SelectMAP mode
- Master SelectMAP mode
- Boundary-Scan mode (IEEE 1532)

A Data Encryption Standard (DES) decryptor is available on-chip to secure the bitstreams. One or two triple-DES key sets can be used to optionally encrypt the configuration data.

The Xilinx System Advanced Configuration Environment (System ACE) family offers high-capacity and flexible solution for FPGA configuration as well as program/data storage for the processor. See [DS080](#), *System ACE CompactFlash Solution* for more information.

### **Readback and Integrated Logic Analyzer**

Configuration data stored in Virtex-II Pro / Virtex-II Pro configuration memory can be read back for verification. Along with the configuration data, the contents of all flip-flops and latches, distributed SelectRAM+, and block SelectRAM+ memory resources can be read back. This capability is useful for real-time debugging.

The Xilinx ChipScope Integrated Logic Analyzer (ILA) cores and Integrated Bus Analyzer (IBA) cores, along with the ChipScope Pro Analyzer software, provide a complete solution for accessing and verifying user designs within Virtex-II Pro devices.

## **IP Core and Reference Support**

Intellectual Property is part of the Platform FPGA solution. In addition to the existing FPGA fabric cores, the list below shows some of the currently available hardware and software intellectual properties specially developed for Virtex-II Pro / Virtex-II Pro X by Xilinx. Each IP core is modular, portable, Real-Time Operating System (RTOS) independent, and CoreConnect compatible for ease of design migration. Refer to [www.xilinx.com/ipcenter](http://www.xilinx.com/ipcenter) for the latest and most complete list of cores.

### **Hardware Cores**

- Bus Infrastructure cores (arbiters, bridges, and more)
- Memory cores (DDR, Flash, and more)
- Peripheral cores (UART, IIC, and more)
- Networking cores (ATM, Ethernet, and more)

### **Software Cores**

- Boot code
- Test code
- Device drivers
- Protocol stacks
- RTOS integration
- Customized board support package

### Output Swing and Emphasis

The output swing and emphasis levels are fully programmable. Each is controlled via attributes at configuration, and can be modified via the PMA attribute programming bus.

The programmable output swing control can adjust the differential peak-to-peak output level between 200 mV and 1600 mV.

With emphasis, the differential voltage swing is boosted to create a stronger rising or falling waveform. This method compensates for high frequency loss in the transmission media that would otherwise limit the magnitude of this waveform. Lossy transmission lines cause the dissipation of electrical energy. This emphasis technique extends the distance that signals can be driven down lossy line media and increases the signal-to-noise ratio at the receiver.

Emphasis can be described from two perspectives, additive to the smaller voltage ( $V_{SM}$ ) (pre-emphasis) or subtractive from the larger voltage ( $V_{LG}$ ) (de-emphasis). The resulting benefits in compensating for channel loss are identical. It is simply a relative way of specifying the effect at the transmitter.

The equations for calculating pre-emphasis as a percentage and dB are as follows:

$$\text{Pre-Emphasis}_{\%} = ((V_{LG} - V_{SM}) / V_{SM}) \times 100$$

$$\text{Pre-Emphasis}_{dB} = 20 \log(V_{LG}/V_{SM})$$

The equations for calculating de-emphasis as a percentage and dB are as follows:

$$\text{De-Emphasis}_{\%} = (V_{LG} - V_{SM}) / V_{LG} \times 100$$

$$\text{De-Emphasis}_{dB} = 20 \log(V_{SM}/V_{LG})$$

The pre-emphasis amount can be programmed in discrete steps between 0% and 500%. The de-emphasis amount can be programmed in discrete steps between 0% and 83%.

### Serializer

The serializer multiplies the reference frequency provided on REFCLK by 10, 16, 20, 32, or 40, depending on the operation mode. The multiplication of the clock is achieved by using an embedded PLL.

Data is converted from parallel to serial format and transmitted on the TXP and TXN differential outputs. The electrical connection of TXP and TXN can be interchanged through configuration. This option can be controlled by an input (TXPOLARITY) at the FPGA transmitter interface.

### Deserializer

Synchronous serial data reception is facilitated by a clock and data recovery (CDR) circuit. This circuit uses a fully monolithic Phase Lock Loop (PLL), which does not require any external components. The CDR circuit extracts both phase and frequency from the incoming data stream.

The derived clock, RXRECCLK, is generated and locked to as long as it remains within the specified component range.

This clock is presented to the FPGA fabric at  $1/10$ ,  $1/16$ ,  $1/20$ ,  $1/32$ , or  $1/40$  the incoming data rate depending on the operating mode.

A sufficient number of transitions must be present in the data stream for CDR to work properly. The CDR circuit is guaranteed to work with 8B/10B and 64B/66B encoding. Further, CDR requires approximately 5,000 transitions upon power-up to guarantee locking to the incoming data rate. Once lock is achieved, up to 75 missing transitions can be tolerated before lock to the incoming data stream is lost.

Another feature of CDR is its ability to accept an external precision reference clock, REFCLK, which either acts to clock incoming data or to assist in synchronizing the derived RXRECCLK.

For further clarity, the TXUSRCLK is used to clock data from the FPGA fabric to the TX FIFO. The FIFO depth accounts for the slight phase difference between these two clocks. If the clocks are locked in frequency, then the FIFO acts much like a pass-through buffer.

The receiver can be configured to reverse the RXP and RXN inputs. This can be useful in the event that printed circuit board traces have been reversed.

### Receiver Lock Control

The CDR circuits will lock to the reference clock automatically if the data is not present. For proper operation, the frequency of the reference clock must be within  $\pm 100$  ppm of the nominal frequency.

During normal operation, the receiver PLL automatically locks to incoming data (when present) or to the local reference clock (when data is not present). This is the default configuration for all primitives. This function can be overridden via the PMARXLOCKSEL port

When receive PLL lock is forced to the local reference, phase information from the incoming data stream is ignored. Data continues to be sampled, but synchronous to the local reference rather than relative to edges in the data stream.

### Receive Equalization

In addition to transmit emphasis, the RocketIO X MGT provides a programmable active receive equalization feature to further compensate the effects of channel attenuation at high frequencies.

By adjusting RXFER, the right amount of equalization can be added to reverse the signal degradation caused by a printed circuit board, a backplane, or a line/switch card. RXFER can be set through software configuration or the PMA Attribute Bus.

### Receiver Termination

On-chip termination is provided at the receiver, eliminating the need for external termination. The receiver termination supply ( $V_{TRX}$ ) is the center tap of differential termination to

## Serializer

The serializer multiplies the reference frequency provided on REFCLK by 20. The multiplication of the clock is achieved by using an embedded PLL.

Data is converted from parallel to serial format and transmitted on the TXP and TXN differential outputs. The electrical connection of TXP and TXN can be interchanged through configuration. This option can be controlled by an input (TXPOLARITY) at the FPGA transmitter interface.

## Deserializer

The serial transceiver input is locked to the input data stream through Clock and Data Recovery (CDR), a built-in feature of the RocketIO transceiver. CDR keys off the rising and falling edges of incoming data and derives a clock that is representative of the incoming data rate.

The derived clock, RXRECCLK, is generated and locked to as long as it remains within the specified component range. This clock is presented to the FPGA fabric at  $1/20$  the incoming data rate.

A sufficient number of transitions must be present in the data stream for CDR to work properly. CDR requires approximately 5,000 transitions upon power-up to guaran-

tee locking to the incoming data rate. Once lock is achieved, up to 75 missing transitions can be tolerated before lock to the incoming data stream is lost. The CDR circuit is guaranteed to work with 8B/10B encoding.

Another feature of CDR is its ability to accept an external precision reference clock, REFCLK, which either acts to clock incoming data or to assist in synchronizing the derived RXRECCLK.

For further clarity, the TXUSRCLK is used to clock data from the FPGA fabric to the TX FIFO. The FIFO depth accounts for the slight phase difference between these two clocks. If the clocks are locked in frequency, then the FIFO acts much like a pass-through buffer.

The receiver can be configured to reverse the RXP and RXN inputs. This can be useful in the event that printed circuit board traces have been reversed.

## Receiver Termination

On-chip termination is provided at the receiver, eliminating the need for external termination. The receiver includes programmable on-chip termination circuitry for  $50\Omega$  (default) or  $75\Omega$  impedance, as shown in Figure 11.

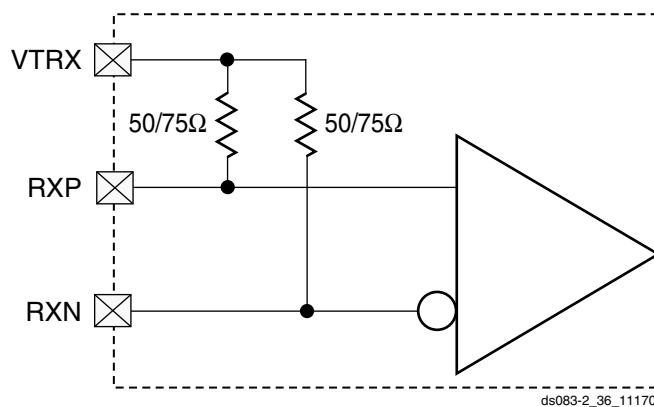


Figure 11: RocketIO Receive Termination

## PCS

### Fabric Data Interface

Internally, the PCS operates in 2-byte mode (16/20 bits). The FPGA fabric interface can either be 1, 2, or 4 bytes wide. When accompanied by the predefined modes of the PMA, the user thus has a large combination of protocols and data rates from which to choose.

USRCLK2 clocks data on the fabric side, while USRCLK clocks data on the PCS side. This creates distinct USRCLK/USRCLK2 frequency ratios for different combina-

tions of fabric and internal data widths. Table 5 summarizes the USRCLK2 to USRCLK ratios for the three fabric data widths.

No fixed phase relationship is assumed between REFCLK, RXRECCLK, and/or any other clock that is not tied to either of these clocks. When RXUSRCLK and RXUSRCLK2 have different frequencies, each edge of the slower clock is aligned to a falling edge of the faster clock. The same relationships apply to TXUSRCLK and TXUSRCLK2.

The Trace port provides instruction execution trace information to an external trace tool. The PPC405 core is capable of back trace and forward trace. Back trace is the tracing of instructions prior to a debug event while forward trace is the tracing of instructions after a debug event.

The processor JTAG port and the FPGA JTAG port can be accessed independently, or the two can be programmatically linked together and accessed via the dedicated FPGA JTAG pins.

For detailed information on the PPC405 JTAG interface, please refer to the "JTAG Interface" section of the [PowerPC 405 Processor Block Reference Guide](#)

### CoreConnect™ Bus Architecture

The Processor Block is compatible with the CoreConnect™ bus architecture. Any CoreConnect compliant cores including Xilinx soft IP can integrate with the Processor Block through this high-performance bus architecture implemented on FPGA fabric.

The CoreConnect architecture provides three buses for interconnecting Processor Blocks, Xilinx soft IP, third party IP, and custom logic, as shown in [Figure 15](#):

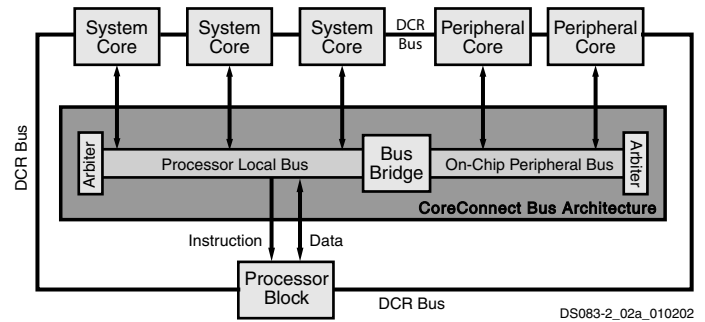


Figure 15: CoreConnect Block Diagram

- Processor Local Bus (PLB)
- On-Chip Peripheral Bus (OPB)
- Device Control Register (DCR) bus

High-performance peripherals connect to the high-bandwidth, low-latency PLB. Slower peripheral cores connect to the OPB, which reduces traffic on the PLB, resulting in greater overall system performance.

For more information, refer to:

[http://www-3.ibm.com/chips/techlib/techlib.nfs/productfamilies/CoreConnect\\_Bus\\_Architecture/](http://www-3.ibm.com/chips/techlib/techlib.nfs/productfamilies/CoreConnect_Bus_Architecture/)

## Functional Description: Embedded PowerPC 405 Core

This section offers a brief overview of the various functional blocks shown in [Figure 16](#).

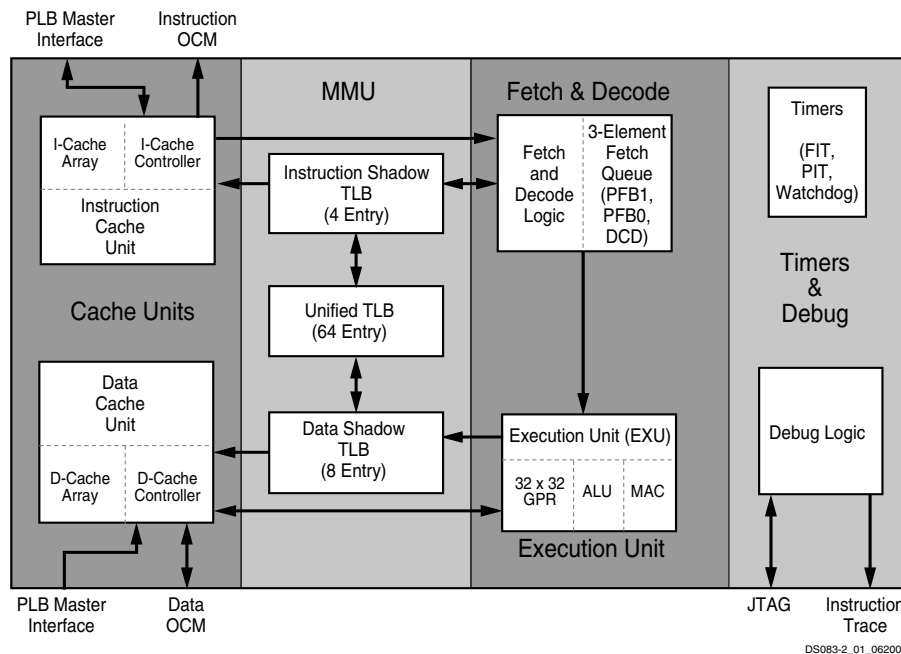


Figure 16: Embedded PPC405 Core Block Diagram

### Embedded PPC405 Core

The embedded PPC405 core is a 32-bit Harvard architecture processor. [Figure 16](#) illustrates its functional blocks:

- Cache units
- Memory Management unit
- Fetch Decode unit



**Table 9: Supported Differential Signal I/O Standards**

I/O Standard	Output V <sub>CCO</sub>	Input V <sub>CCO</sub>	Input V <sub>REF</sub>	Output V <sub>OD</sub>
LDT_25	2.5	N/R	N/R	0.500 – 0.740
LVDS_25	2.5	N/R	N/R	0.247 – 0.454
LVDSEXT_25	2.5	N/R	N/R	0.440 – 0.820
BLVDS_25	2.5	N/R	N/R	0.250 – 0.450
ULVDS_25	2.5	N/R	N/R	0.500 – 0.740
LVPECL_25	2.5	N/R	N/R	0.345 – 1.185
LDT_25_DT <sup>(1)</sup>	2.5	2.5	N/R	0.500 – 0.740
LVDS_25_DT <sup>(1)</sup>	2.5	2.5	N/R	0.247 – 0.454
LVDSEXT_25_DT <sup>(1)</sup>	2.5	2.5	N/R	0.330 – 0.700
ULVDS_25_DT <sup>(1)</sup>	2.5	2.5	N/R	0.500 – 0.740

**Notes:**

1. These standards support on-chip 100Ω termination.
2. N/R = no requirement.

**Table 10: Supported DCI I/O Standards**

I/O Standard	Output V <sub>CCO</sub>	Input V <sub>CCO</sub>	Input V <sub>REF</sub>	Termination Type
LVDCI_33 <sup>(1)</sup>	3.3	3.3	N/R	Series
LVDCI_25	2.5	2.5	N/R	Series
LVDCI_DV2_25	2.5	2.5	N/R	Series
LVDCI_18	1.8	1.8	N/R	Series
LVDCI_DV2_18	1.8	1.8	N/R	Series
LVDCI_15	1.5	1.5	N/R	Series
LVDCI_DV2_15	1.5	1.5	N/R	Series
GTL_DCI	1.2	1.2	0.8	Single
GTLP_DCI	1.5	1.5	1.0	Single
HSTL_I_DCI	1.5	1.5	0.75	Split
HSTL_II_DCI	1.5	1.5	0.75	Split
HSTL_III_DCI	1.5	1.5	0.9	Single
HSTL_IV_DCI	1.5	1.5	0.9	Single
HSTL_I_DCI_18	1.8	1.8	0.9	Split
HSTL_II_DCI_18	1.8	1.8	0.9	Split
HSTL_III_DCI_18	1.8	1.8	1.1	Single
HSTL_IV_DCI_18	1.8	1.8	1.1	Single
SSTL2_I_DCI <sup>(2)</sup>	2.5	2.5	1.25	Split
SSTL2_II_DCI <sup>(2)</sup>	2.5	2.5	1.25	Split
SSTL18_I_DCI <sup>(3)</sup>	1.8	1.8	0.9	Split
SSTL18_II_DCI	1.8	1.8	0.9	Split

**Table 10: Supported DCI I/O Standards (Continued)**

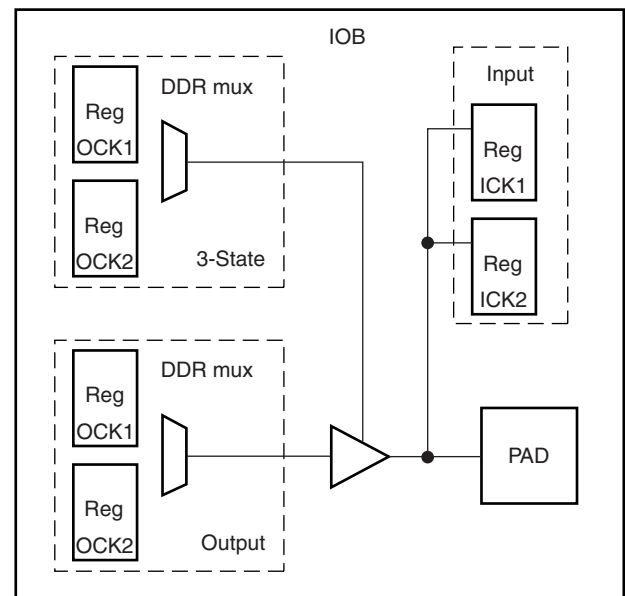
I/O Standard	Output V <sub>CCO</sub>	Input V <sub>CCO</sub>	Input V <sub>REF</sub>	Termination Type
LVDS_25_DCI	2.5	2.5	N/R	Split
LVDSEXT_25_DCI	2.5	2.5	N/R	Split

**Notes:**

1. LVDCI\_XX is LVCMOS output controlled impedance buffers, matching all or half of the reference resistors.
2. These are SSTL compatible.
3. SSTL18\_I is not a JEDEC-supported standard.
4. N/R = no requirement.

## Logic Resources

IOB blocks include six storage elements, as shown in Figure 19.



DS031\_29\_100900

**Figure 19: Virtex-II Pro IOB Block**

Each storage element can be configured either as an edge-triggered D-type flip-flop or as a level-sensitive latch. On the input, output, and 3-state path, one or two DDR registers can be used.

Double data rate is directly accomplished by the two registers on each path, clocked by the rising edges (or falling edges) from two different clock nets. The two clock signals are generated by the DCM and must be 180 degrees out of phase, as shown in Figure 20. There are two input, output, and 3-state data signals, each being alternately clocked out.

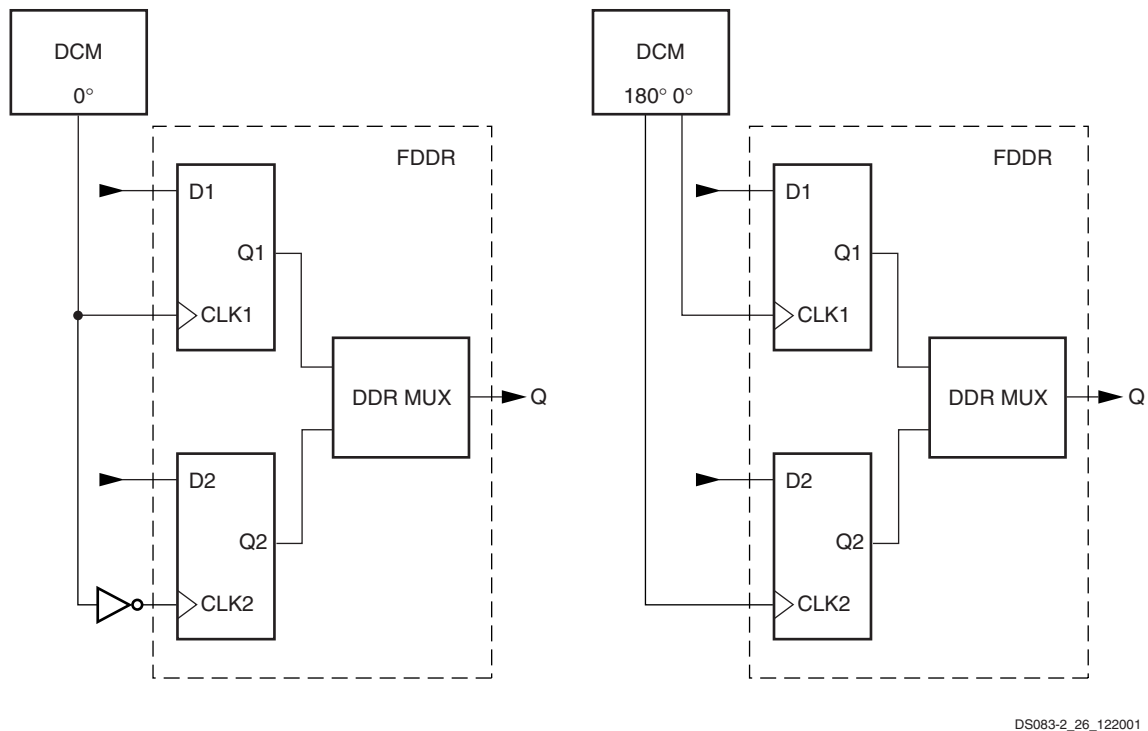


Figure 20: Double Data Rate Registers

This DDR mechanism can be used to mirror a copy of the clock on the output. This is useful for propagating a clock along the data that has an identical delay. It is also useful for multiple clock generation, where there is a unique clock driver for every clock load. Virtex-II Pro devices can produce many copies of a clock with very little skew.

Each group of two registers has a clock enable signal (ICE for the input registers, OCE for the output registers, and TCE for the 3-state registers). The clock enable signals are active High by default. If left unconnected, the clock enable for that storage element defaults to the active state.

Each IOB block has common synchronous or asynchronous set and reset (SR and REV signals). Two neighboring IOBs have a shared routing resource connecting the ICLK and OTCLK pins on pairs of IOBs. If two adjacent IOBs using DDR registers do not share the same clock signals on their clock pins (ICLK1, ICLK2, OTCLK1, and OTCLK2), one of the clock signals will be unroutable.

The IOB pairing is identical to the LVDS IOB pairs. Hence, the package pin-out table can also be used for pin assignment to avoid conflict.

SR forces the storage element into the state specified by the SRHIGH or SRLOW attribute. SRHIGH forces a logic 1. SRLOW forces a logic "0". When SR is used, a second input

(REV) forces the storage element into the opposite state. The reset condition predominates over the set condition. The initial state after configuration or global initialization state is defined by a separate INIT0 and INIT1 attribute. By default, the SRLOW attribute forces INIT0, and the SRHIGH attribute forces INIT1.

For each storage element, the SRHIGH, SRLOW, INIT0, and INIT1 attributes are independent. Synchronous or asynchronous set / reset is consistent in an IOB block.

All the control signals have independent polarity. Any inverter placed on a control input is automatically absorbed.

Each register or latch, independent of all other registers or latches, can be configured as follows:

- No set or reset
- Synchronous set
- Synchronous reset
- Synchronous set and reset
- Asynchronous set (preset)
- Asynchronous reset (clear)
- Asynchronous set and reset (preset and clear)

The synchronous reset overrides a set, and an asynchronous clear overrides a preset.

Refer to [Figure 21](#).



## Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

DS083 (v5.0) June 21, 2011

Product Specification

### Virtex-II Pro<sup>(1)</sup> Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade

commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

### Virtex-II Pro DC Characteristics

Table 1: Absolute Maximum Ratings

Symbol	Description <sup>(1)</sup>		Virtex-II Pro X	Virtex-II Pro	Units
V <sub>CCINT</sub>	Internal supply voltage relative to GND		-0.5 to 1.6		V
V <sub>CCAUX</sub>	Auxiliary supply voltage relative to GND		-0.5 to 3.0		V
V <sub>CCO</sub>	Output drivers supply voltage relative to GND		-0.5 to 3.75		V
V <sub>BATT</sub>	Key memory battery backup supply		-0.5 to 4.05		V
V <sub>REF</sub>	Input reference voltage		-0.3 to 3.75		V
V <sub>IN</sub>	3.3V I/O input voltage relative to GND (user and dedicated I/Os)		-0.3 to 4.05 <sup>(3)</sup>		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)		-0.5 to V <sub>CCO</sub> + 0.5		V
V <sub>TS</sub>	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)		-0.3 to 4.05 <sup>(3)</sup>		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)		-0.5 to V <sub>CCO</sub> + 0.5		V
AVCCAUXRX	Receive auxiliary supply voltage relative to GNDA (analog ground)		-0.5 to 2.0	-0.5 to 3.0	V
AVCCAUTX	Transmit auxiliary supply voltage relative to GNDA (analog ground)		-0.5 to 3.0	-0.5 to 3.0	V
V <sub>TRX</sub>	Terminal receive supply voltage relative to GND		-0.5 to 3.0	-0.5 to 3.0	V
V <sub>TTX</sub>	Terminal transmit supply voltage relative to GND		-0.5 to 1.6	-0.5 to 3.0	V
T <sub>STG</sub>	Storage temperature (ambient)		-65 to +150		°C
T <sub>SOL</sub>	Maximum soldering temperature <sup>(2)</sup>	All regular FG/FF flip-chip packages	+220		°C
		Pb-free FGG256 wire-bond package	N/A	+260	°C
		Pb-free FGG456 and FGG676 wire-bond packages	N/A	+250	°C
T <sub>J</sub>	Maximum junction temperature <sup>(2)</sup>		+125		°C

#### Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. For soldering guidelines and thermal considerations, see the [Device Packaging and Thermal Characteristics Guide](#) information on the Xilinx website.
3. 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to [XAPP659](#) for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.



## Virtex-II Pro Performance Characteristics

This section provides the performance characteristics of some common functions and designs implemented in Virtex-II Pro devices. The numbers reported here are fully characterized worst-case values. Note that these values are subject to the same guidelines as [Virtex-II Pro Switching Characteristics](#) (speed files).

**Table 13** provides pin-to-pin values (in nanoseconds) including IOB delays; that is, delay through the device from input pin to output pin. In the case of multiple inputs and outputs, the worst delay is reported.

*Table 13: Pin-to-Pin Performance*

Description	Device Used & Speed Grade	Pin-to-Pin Performance (with I/O Delays)	Units
<b>Basic Functions:</b>			
16-bit Address Decoder	XC2VP20FF1152-6	7.20	ns
32-bit Address Decoder	XC2VP20FF1152-6	8.08	ns
64-bit Address Decoder	XC2VP20FF1152-6	8.15	ns
4:1 MUX	XC2VP20FF1152-6	3.85	ns
8:1 MUX	XC2VP20FF1152-6	7.24	ns
16:1 MUX	XC2VP20FF1152-6	7.30	ns
32:1 MUX	XC2VP20FF1152-6	7.64	ns
Combinatorial (pad to LUT to pad)	XC2VP20FF1152-6	3.26	ns
<b>Memory:</b>			
<b>Block RAM</b>			
Pad to setup	XC2VP20FF1152-6	1.72	ns
Clock to Pad	XC2VP20FF1152-6	6.63	ns
<b>Distributed RAM</b>			
Pad to setup	XC2VP20FF1152-6	1.78	ns
Clock to Pad	XC2VP20FF1152-6	4.12	ns

**Table 46: Pipelined Multiplier Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Setup and Hold Times Before/After Clock					
Data Inputs	T <sub>MULIDCK</sub> /T <sub>MULCKID</sub>	1.86/ 0.00	2.06/ 0.00	2.31/ 0.00	ns, max
Clock Enable	T <sub>MULIDCK_CE</sub> /T <sub>MULCKID_CE</sub>	0.23/ 0.00	0.25/ 0.00	0.28/ 0.00	ns, max
Reset	T <sub>MULIDCK_RST</sub> /T <sub>MULCKID_RST</sub>	0.21/–0.09	0.24/–0.09	0.26/–0.10	ns, max
Clock to Output Pin					
Clock to Pin35	T <sub>MULTCK_P35</sub>	2.45	2.92	3.27	ns, max
Clock to Pin34	T <sub>MULTCK_P34</sub>	2.36	2.82	3.16	ns, max
Clock to Pin33	T <sub>MULTCK_P33</sub>	2.28	2.72	3.05	ns, max
Clock to Pin32	T <sub>MULTCK_P32</sub>	2.20	2.62	2.93	ns, max
Clock to Pin31	T <sub>MULTCK_P31</sub>	2.12	2.52	2.82	ns, max
Clock to Pin30	T <sub>MULTCK_P30</sub>	2.03	2.42	2.71	ns, max
Clock to Pin29	T <sub>MULTCK_P29</sub>	1.95	2.32	2.60	ns, max
Clock to Pin28	T <sub>MULTCK_P28</sub>	1.87	2.22	2.48	ns, max
Clock to Pin27	T <sub>MULTCK_P27</sub>	1.79	2.12	2.37	ns, max
Clock to Pin26	T <sub>MULTCK_P26</sub>	1.70	2.02	2.26	ns, max
Clock to Pin25	T <sub>MULTCK_P25</sub>	1.62	1.92	2.15	ns, max
Clock to Pin24	T <sub>MULTCK_P24</sub>	1.54	1.82	2.03	ns, max
Clock to Pin23	T <sub>MULTCK_P23</sub>	1.46	1.71	1.92	ns, max
Clock to Pin22	T <sub>MULTCK_P22</sub>	1.37	1.61	1.81	ns, max
Clock to Pin21	T <sub>MULTCK_P21</sub>	1.29	1.51	1.69	ns, max
Clock to Pin20	T <sub>MULTCK_P20</sub>	1.21	1.41	1.58	ns, max
Clock to Pin19	T <sub>MULTCK_P19</sub>	1.13	1.31	1.47	ns, max
Clock to Pin18	T <sub>MULTCK_P18</sub>	1.04	1.21	1.36	ns, max
Clock to Pin17	T <sub>MULTCK_P17</sub>	0.96	1.11	1.24	ns, max
Clock to Pin16	T <sub>MULTCK_P16</sub>	0.88	1.01	1.13	ns, max
Clock to Pin15	T <sub>MULTCK_P15</sub>	0.80	0.91	1.02	ns, max
Clock to Pin14	T <sub>MULTCK_P14</sub>	0.71	0.81	0.91	ns, max
Clock to Pin13	T <sub>MULTCK_P13</sub>	0.63	0.71	0.79	ns, max
Clock to Pin12	T <sub>MULTCK_P12</sub>	0.63	0.71	0.79	ns, max
Clock to Pin11	T <sub>MULTCK_P11</sub>	0.63	0.71	0.79	ns, max
Clock to Pin10	T <sub>MULTCK_P10</sub>	0.63	0.71	0.79	ns, max
Clock to Pin9	T <sub>MULTCK_P9</sub>	0.63	0.71	0.79	ns, max
Clock to Pin8	T <sub>MULTCK_P8</sub>	0.63	0.71	0.79	ns, max
Clock to Pin7	T <sub>MULTCK_P7</sub>	0.63	0.71	0.79	ns, max
Clock to Pin6	T <sub>MULTCK_P6</sub>	0.63	0.71	0.79	ns, max
Clock to Pin5	T <sub>MULTCK_P5</sub>	0.63	0.71	0.79	ns, max
Clock to Pin4	T <sub>MULTCK_P4</sub>	0.63	0.71	0.79	ns, max
Clock to Pin3	T <sub>MULTCK_P3</sub>	0.63	0.71	0.79	ns, max
Clock to Pin2	T <sub>MULTCK_P2</sub>	0.63	0.71	0.79	ns, max
Clock to Pin1	T <sub>MULTCK_P1</sub>	0.63	0.71	0.79	ns, max
Clock to Pin0	T <sub>MULTCK_P0</sub>	0.63	0.71	0.79	ns, max

## Input Clock Tolerances

Table 58: Input Clock Tolerances

Description	Symbol	Constraints  F <sub>CLKIN</sub>	Speed Grade						Units
			−7		−6		−5		
			Min	Max	Min	Max	Min	Max	
Input Clock Low/High Pulse Width									
PSCLK	PSCLK_PULSE	< 1MHz	25.00		25.00		25.00		ns
PSCLK and CLKIN <sup>(3)</sup>	PSCLK_PULSE and CLKIN_PULSE	1 – 10 MHz	25.00		25.00		25.00		ns
		10 – 25 MHz	10.00		10.00		10.00		ns
		25 – 50 MHz	5.00		5.00		5.00		ns
		50 – 100 MHz	3.00		3.00		3.00		ns
		100 – 150 MHz	2.40		2.40		2.40		ns
		150 – 200 MHz	2.00		2.00		2.00		ns
		200 – 250 MHz	1.80		1.80		1.80		ns
		250 – 300 MHz	1.50		1.50		1.50		ns
		300 – 350 MHz	1.30		1.30		1.30		ns
		350 – 400 MHz	1.15		1.15		1.15		ns
> 400 MHz	1.05		1.05		1.05		ns		
Input Clock Cycle-Cycle Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs) <sup>(1)</sup>	CLKIN_CYC_JITT_DLL_LF			±300		±300		±300	ps
CLKIN (using CLKFX outputs) <sup>(2)</sup>	CLKIN_CYC_JITT_FX_LF			±300		±300		±300	ps
Input Clock Cycle-Cycle Jitter (High Frequency Mode)									
CLKIN (using DLL outputs) <sup>(1)</sup>	CLKIN_CYC_JITT_DLL_HF			±150		±150		±150	ps
CLKIN (using CLKFX outputs) <sup>(2)</sup>	CLKIN_CYC_JITT_FX_HF			±150		±150		±150	ps
Input Clock Period Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs) <sup>(1)</sup>	CLKIN_PER_JITT_DLL_LF			±1		±1		±1	ns
CLKIN (using CLKFX outputs) <sup>(2)</sup>	CLKIN_PER_JITT_FX_LF			±1		±1		±1	ns
Input Clock Period Jitter (High Frequency Mode)									
CLKIN (using DLL outputs) <sup>(1)</sup>	CLKIN_PER_JITT_DLL_HF			±1		±1		±1	ns
CLKIN (using CLKFX outputs) <sup>(2)</sup>	CLKIN_PER_JITT_FX_HF			±1		±1		±1	ns
Feedback Clock Path Delay Variation									
CLKFB off-chip feedback	CLKFB_DELAY_VAR_EXT			±1		±1		±1	ns

### Notes:

1. "DLL outputs" is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. If both DLL and CLKFX outputs are used, follow the more restrictive specification.
3. If DCM phase shift feature is used and CLKIN frequency > 200 Mhz, CLKIN duty cycle must be within ±5% (45/55 to 55/45).

## Miscellaneous Timing Parameters

Table 61: Miscellaneous Timing Parameters

			Speed Grade			
Description	Symbol	Constraints F <sub>CLKIN</sub>	-7	-6	-5	Units
<b>Time Required to Achieve LOCK</b>						
Using DLL outputs <sup>(1)</sup>	LOCK_DLL:					
	LOCK_DLL_60	> 60MHz	20.00	20.00	20.00	us
	LOCK_DLL_50_60	50 - 60 MHz	25.00	25.00	25.00	us
	LOCK_DLL_40_50	40 - 50 MHz	50.00	50.00	50.00	us
	LOCK_DLL_30_40	30 - 40 MHz	90.00	90.00	90.00	us
	LOCK_DLL_24_30	24 - 30 MHz	120.00	120.00	120.00	us
Using CLKFX outputs	LOCK_FX_MIN		10.00	10.00	10.00	ms
	LOCK_FX_MAX		10.00	10.00	10.00	ms
Additional lock time with fine phase shifting	LOCK_DLL_FINE_SHIFT		50.00	50.00	50.00	us
<b>Fine Phase Shifting</b>						
Absolute shifting range	FINE_SHIFT_RANGE		10.00	10.00	10.00	ns
<b>Delay Lines</b>						
Tap delay resolution	DCM_TAP_MIN		30.00	30.00	30.00	ps
	DCM_TAP_MAX		50.00	50.00	50.00	ps

**Notes:**

1. "DLL outputs" is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.

## Frequency Synthesis

Table 62: Frequency Synthesis

Attribute	Min	Max
CLKFX_MULTIPLY	2	32
CLKFX_DIVIDE	1	32

## Parameter Cross-Reference

Table 63: Parameter Cross-Reference

Libraries Guide	Data Sheet
DLL_CLKOUT_{MINIMAX}_LF	CLKOUT_FREQ_{1X 2X DV}_LF
DFS_CLKOUT_{MINIMAX}_LF	CLKOUT_FREQ_FX_LF
DLL_CLKIN_{MINIMAX}_LF	CLKIN_FREQ_DLL_LF
DFS_CLKIN_{MINIMAX}_LF	CLKIN_FREQ_FX_LF
DLL_CLKOUT_{MINIMAX}_HF	CLKOUT_FREQ_{1X DV}_HF
DFS_CLKOUT_{MINIMAX}_HF	CLKOUT_FREQ_FX_HF
DLL_CLKIN_{MINIMAX}_HF	CLKIN_FREQ_DLL_HF
DFS_CLKIN_{MINIMAX}_HF	CLKIN_FREQ_FX_HF

Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	IO_L88N_7/VREF_7	L5			
7	IO_L86P_7	L6			
7	IO_L86N_7	K6			
7	IO_L85P_7	K1			
7	IO_L85N_7	K2			
7	IO_L60P_7	K3	NC		
7	IO_L60N_7	K4	NC		
7	IO_L58P_7	K5	NC		
7	IO_L58N_7/VREF_7	J5	NC		
7	IO_L56P_7	J1	NC		
7	IO_L56N_7	J2	NC		
7	IO_L55P_7	J3	NC		
7	IO_L55N_7	J4	NC		
7	IO_L54P_7	J6	NC		
7	IO_L54N_7	H5	NC		
7	IO_L52P_7	H1	NC		
7	IO_L52N_7/VREF_7	H2	NC		
7	IO_L50P_7	H3	NC		
7	IO_L50N_7	H4	NC		
7	IO_L49P_7	G1	NC		
7	IO_L49N_7	G2	NC		
7	IO_L48P_7	G3	NC		
7	IO_L48N_7	G4	NC		
7	IO_L46P_7	G5	NC		
7	IO_L46N_7/VREF_7	F5	NC		
7	IO_L43P_7	F1	NC		
7	IO_L43N_7	F2	NC		
7	IO_L06P_7	F3			
7	IO_L06N_7	F4			
7	IO_L04P_7	E1			
7	IO_L04N_7/VREF_7	E2			
7	IO_L03P_7	E3			
7	IO_L03N_7	E4			
7	IO_L02P_7	D1			
7	IO_L02N_7	D2			
7	IO_L01P_7/VRN_7	C1			
7	IO_L01N_7/VRP_7	C2			



Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	VCCAUX	L1			
N/A	VCCAUX	B21			
N/A	VCCAUX	B2			
N/A	VCCAUX	AB11			
N/A	VCCAUX	AA21			
N/A	VCCAUX	AA2			
N/A	VCCAUX	A12			
N/A	GND	Y3			
N/A	GND	Y20			
N/A	GND	W4			
N/A	GND	W19			
N/A	GND	V5			
N/A	GND	V18			
N/A	GND	P9			
N/A	GND	P14			
N/A	GND	P13			
N/A	GND	P12			
N/A	GND	P11			
N/A	GND	P10			
N/A	GND	N9			
N/A	GND	N14			
N/A	GND	N13			
N/A	GND	N12			
N/A	GND	N11			
N/A	GND	N10			
N/A	GND	M9			
N/A	GND	M14			
N/A	GND	M13			
N/A	GND	M12			
N/A	GND	M11			
N/A	GND	M10			
N/A	GND	M1			
N/A	GND	L9			
N/A	GND	L22			
N/A	GND	L14			
N/A	GND	L13			
N/A	GND	L12			

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L01P_6/VRN_6	AJ30				
6	IO_L01N_6/VRP_6	AJ31				
6	IO_L02P_6	AJ27				
6	IO_L02N_6	AJ28				
6	IO_L03P_6	AK31				
6	IO_L03N_6/VREF_6	AK32				
6	IO_L04P_6	AH29				
6	IO_L04N_6	AH30				
6	IO_L05P_6	AH27				
6	IO_L05N_6	AG28				
6	IO_L06P_6	AL33				
6	IO_L06N_6	AL34				
6	IO_L15P_6	AG29	NC			
6	IO_L15N_6/VREF_6	AG30	NC			
6	IO_L16P_6	AK33	NC			
6	IO_L16N_6	AK34	NC			
6	IO_L17P_6	AF27	NC			
6	IO_L17N_6	AF28	NC			
6	IO_L18P_6	AJ33	NC			
6	IO_L18N_6	AJ34	NC			
6	IO_L19P_6	AH31	NC			
6	IO_L19N_6	AH32	NC			
6	IO_L20P_6	AD25	NC			
6	IO_L20N_6	AD26	NC			
6	IO_L21P_6	AG31	NC			
6	IO_L21N_6/VREF_6	AG32	NC			
6	IO_L22P_6	AF29	NC			
6	IO_L22N_6	AF30	NC			
6	IO_L23P_6	AE27	NC			
6	IO_L23N_6	AE28	NC			
6	IO_L24P_6	AH33	NC			
6	IO_L24N_6	AH34	NC			
6	IO_L31P_6	AF31				
6	IO_L31N_6	AF32				
6	IO_L32P_6	AC25				
6	IO_L32N_6	AC26				
6	IO_L33P_6	AG33				
6	IO_L33N_6/VREF_6	AG34				

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L21P_2	E6		
2	IO_L22N_2/VREF_2	F7		
2	IO_L22P_2	F8		
2	IO_L23N_2	M10		
2	IO_L23P_2	L10		
2	IO_L24N_2	G5		
2	IO_L24P_2	F5		
2	IO_L25N_2	F3		
2	IO_L25P_2	F4		
2	IO_L26N_2	M8		
2	IO_L26P_2	M9		
2	IO_L27N_2	F1		
2	IO_L27P_2	F2		
2	IO_L28N_2/VREF_2	G6		
2	IO_L28P_2	G7		
2	IO_L29N_2	M7		
2	IO_L29P_2	N8		
2	IO_L30N_2	G3		
2	IO_L30P_2	H4		
2	IO_L31N_2	G1		
2	IO_L31P_2	G2		
2	IO_L32N_2	N10		
2	IO_L32P_2	N11		
2	IO_L33N_2	H5		
2	IO_L33P_2	H6		
2	IO_L34N_2/VREF_2	H2		
2	IO_L34P_2	H3		
2	IO_L35N_2	N6		
2	IO_L35P_2	N7		
2	IO_L36N_2	K4		
2	IO_L36P_2	J4		
2	IO_L37N_2	J2		
2	IO_L37P_2	J3		
2	IO_L38N_2	P10		
2	IO_L38P_2	P11		
2	IO_L39N_2	K5		
2	IO_L39P_2	K6		
2	IO_L40N_2/VREF_2	L3		

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
7	IO_L51P_7	N31		
7	IO_L51N_7	P31		
7	IO_L50P_7	T27		
7	IO_L50N_7	R28		
7	IO_L49P_7	M33		
7	IO_L49N_7	M34		
7	IO_L48P_7	M31		
7	IO_L48N_7	M32		
7	IO_L47P_7	R24		
7	IO_L47N_7	R25		
7	IO_L46P_7	M29		
7	IO_L46N_7/VREF_7	M30		
7	IO_L45P_7	L33		
7	IO_L45N_7	L34		
7	IO_L44P_7	P27		
7	IO_L44N_7	P28		
7	IO_L43P_7	L29		
7	IO_L43N_7	L30		
7	IO_L42P_7	K33		
7	IO_L42N_7	K34		
7	IO_L41P_7	P26		
7	IO_L41N_7	R26		
7	IO_L40P_7	K32		
7	IO_L40N_7/VREF_7	L32		
7	IO_L39P_7	K29		
7	IO_L39N_7	K30		
7	IO_L38P_7	P24		
7	IO_L38N_7	P25		
7	IO_L37P_7	J32		
7	IO_L37N_7	J33		
7	IO_L36P_7	J31		
7	IO_L36N_7	K31		
7	IO_L35P_7	N28		
7	IO_L35N_7	N29		
7	IO_L34P_7	H32		
7	IO_L34N_7/VREF_7	H33		
7	IO_L33P_7	H29		
7	IO_L33N_7	H30		

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
7	IO_L32P_7	N24		
7	IO_L32N_7	N25		
7	IO_L31P_7	G33		
7	IO_L31N_7	G34		
7	IO_L30P_7	H31		
7	IO_L30N_7	G32		
7	IO_L29P_7	N27		
7	IO_L29N_7	M28		
7	IO_L28P_7	G28		
7	IO_L28N_7/VREF_7	G29		
7	IO_L27P_7	F33		
7	IO_L27N_7	F34		
7	IO_L26P_7	M26		
7	IO_L26N_7	M27		
7	IO_L25P_7	F31		
7	IO_L25N_7	F32		
7	IO_L24P_7	F30		
7	IO_L24N_7	G30		
7	IO_L23P_7	L25		
7	IO_L23N_7	M25		
7	IO_L22P_7	F27		
7	IO_L22N_7/VREF_7	F28		
7	IO_L21P_7	E29		
7	IO_L21N_7	F29		
7	IO_L20P_7	L28		
7	IO_L20N_7	K28		
7	IO_L19P_7	D33		
7	IO_L19N_7	D34		
7	IO_L18P_7	D32		
7	IO_L18N_7	E32		
7	IO_L17P_7	K26		
7	IO_L17N_7	L26		
7	IO_L16P_7	D31		
7	IO_L16N_7/VREF_7	E31		
7	IO_L15P_7	D29		
7	IO_L15N_7	D30		
7	IO_L14P_7	J28		
7	IO_L14N_7	J29		



Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	M2	AJ29		
N/A	TCK	E8		
N/A	TDI	L30		
N/A	TDO	L10		
N/A	TMS	F9		
N/A	PWRDWN_B	AP9		
N/A	HSWAP_EN	E32		
N/A	RSVD	D8		
N/A	VBATT	L11		
N/A	DXP	L29		
N/A	DXN	F31		
N/A	AVCCAUXTX2	B35		
N/A	VTTXPAD2	B36		
N/A	TXNPAD2	A36		
N/A	TXPPAD2	A35		
N/A	GND A2	C34		
N/A	RXPPAD2	A34		
N/A	RXNPAD2	A33		
N/A	VTRXPAD2	B34		
N/A	AVCCAUXRX2	B33		
N/A	AVCCAUXTX4	B31		
N/A	VTTXPAD4	B32		
N/A	TXNPAD4	A32		
N/A	TXPPAD4	A31		
N/A	GND A4	C31		
N/A	RXPPAD4	A30		
N/A	RXNPAD4	A29		
N/A	VTRXPAD4	B30		
N/A	AVCCAUXRX4	B29		
N/A	AVCCAUXTX5	B27		
N/A	VTTXPAD5	B28		
N/A	TXNPAD5	A28		
N/A	TXPPAD5	A27		
N/A	GND A5	C27		
N/A	RXPPAD5	A26		
N/A	RXNPAD5	A25		
N/A	VTRXPAD5	B26		
N/A	AVCCAUXRX5	B25		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND A18	AU16		
N/A	TXPPAD18	AW18		
N/A	TXNPAD18	AW19		
N/A	VTTXPAD18	AV19		
N/A	AVCCAUXTX18	AV18		
N/A	AVCCAUXRX19	AV21		
N/A	VTRXPAD19	AV22		
N/A	RXNPAD19	AW21		
N/A	RXPPAD19	AW22		
N/A	GND A19	AU24		
N/A	TXPPAD19	AW23		
N/A	TXNPAD19	AW24		
N/A	VTTXPAD19	AV24		
N/A	AVCCAUXTX19	AV23		
N/A	AVCCAUXRX20	AV25		
N/A	VTRXPAD20	AV26		
N/A	RXNPAD20	AW25		
N/A	RXPPAD20	AW26		
N/A	GND A20	AU27		
N/A	TXPPAD20	AW27		
N/A	TXNPAD20	AW28		
N/A	VTTXPAD20	AV28		
N/A	AVCCAUXTX20	AV27		
N/A	AVCCAUXRX21	AV29		
N/A	VTRXPAD21	AV30		
N/A	RXNPAD21	AW29		
N/A	RXPPAD21	AW30		
N/A	GND A21	AU31		
N/A	TXPPAD21	AW31		
N/A	TXNPAD21	AW32		
N/A	VTTXPAD21	AV32		
N/A	AVCCAUXTX21	AV31		
N/A	AVCCAUXRX23	AV33		
N/A	VTRXPAD23	AV34		
N/A	RXNPAD23	AW33		
N/A	RXPPAD23	AW34		
N/A	GND A23	AU34		
N/A	TXPPAD23	AW35		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
0	IO_L67P_0	J22	
0	IO_L68N_0	K23	
0	IO_L68P_0	L23	
0	IO_L69N_0	F22	
0	IO_L69P_0/VREF_0	G22	
0	IO_L73N_0	D22	
0	IO_L73P_0	E22	
0	IO_L74N_0/GCLK7P	K22	
0	IO_L74P_0/GCLK6S	L22	
0	IO_L75N_0/GCLK5P	B22	
0	IO_L75P_0/GCLK4S	C22	
1	IO_L75N_1/GCLK3P	C21	
1	IO_L75P_1/GCLK2S	B21	
1	IO_L74N_1/GCLK1P	L21	
1	IO_L74P_1/GCLK0S	K21	
1	IO_L73N_1	E21	
1	IO_L73P_1	D21	
1	IO_L69N_1/VREF_1	G21	
1	IO_L69P_1	F21	
1	IO_L68N_1	L20	
1	IO_L68P_1	K20	
1	IO_L67N_1	J21	
1	IO_L67P_1	H21	
1	IO_L66N_1/VREF_1	C20	
1	IO_L66P_1	B20	
1	IO_L65N_1	M20	
1	IO_L65P_1	M21	
1	IO_L64N_1	G20	
1	IO_L64P_1	F20	
1	IO_L60N_1	B19	
1	IO_L60P_1	A19	
1	IO_L59N_1	K19	
1	IO_L59P_1	J19	
1	IO_L58N_1	D19	
1	IO_L58P_1	D20	
1	IO_L57N_1/VREF_1	F19	